

Ultra Low Capacitance Array for ESD Protection

The MESD3310 provides a typical line to line capacitance of 0.08pF between I/O pins and low insertion loss up to 3GHz providing greater signal integrity making it ideally suited for HDMI applications, such as Digital TVs, DVD players, Computing, set-top boxes and MDDI applications in mobile computing devices.

It has been specifically designed to protect sensitive components which are connected to high-speed data and transmission lines from overvoltage caused by ESD(electrostatic discharge), CDE (Cable Discharge Events), and EFT (electrical fast transients).

Features

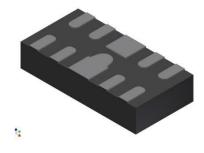
- Protects two or four I/O lines
- Low capacitance:0.08pf Typical between I/O channel
- Working voltages: 3.3V
- Low leakage current
- Response Time is < 1 ns
- Meets MSL 1 Requirements
- SCR technology
- ROHS compliant

Main applications

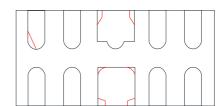
- High Definition Multi-Media Interface (HDMI1.3/1.4/2.0)
- Digital Visual Interface (DVI)
- Display Port Interface
- Serial ATA
- PCI Express
- USB 1.1/2.0/3.0/3.1/OTG
- IEEE 1394 Firewire Ports
- Projection TV Monitors and Flat Panel Displays
- Notebook Computers
- Set Top Box
- Projection TV

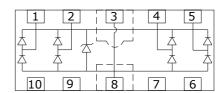
Protection solution to meet

- IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)



DFN2510





Ordering Information

Device Marking		Qty per Reel	Reel Size	
MESD3310	3324P	3000	7 Inch	





Force mos

Maximum ratings (Tamb=25°C Unless Otherwise Specified)						
Parameter	Symbol	Value	Unit			
ESD Rating per IEC61000-4-2: Contact		18	1/3/			
Air		18	KV			
Lead Soldering Temperature	T_L	260 (10 sec.)	°C			
Operating Temperature Range	Tı	-55 ~ 150	°C			
Storage Temperature Range	Тѕтс	-55 ~ 150	°C			

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

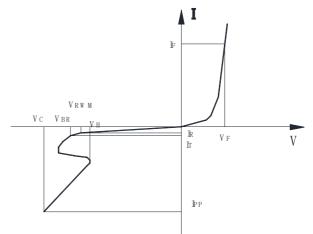
^{1.} Non-repetitive current pulse, per Figure 1.

Electrical characteristics (Tamb=25°C Unless Otherwise Specified)								
Symbol	Parameter	Conditions Min.		Тур.	Max.	Units		
$V_{\scriptscriptstyle \mathrm{RWM}}$	Reverse Working Voltage	Any I/O to Ground			3.3	V		
$V_{\scriptscriptstyle BR}$	Reverse Breakdown Voltage	$I_T = 0.1 \text{mA},$	4.0			V		
$I_{\scriptscriptstyle R}$	Reverse Leakage Current	$V_{RWM} = 3.3V$,			1	μΑ		
$V_{\scriptscriptstyle F}$	Diode Forward Voltage	$I_F = 15 \text{mA}$		0.85	1.2	V		
$V_{\scriptscriptstyle h}$	Hold Current Voltage	$I_H = 10 \text{mA}$		1.85		V		
V	Clamping Voltage	$I_{PP} = 1A^{(1)},$		1.7		V		
V_c		$I_{PP} = 16A^{(1)},$		5.1		V		
D	dynamic resistance	positive transient(TLP)		0.26		Ω		
R _{dyn}		negative transient(TLP)		0.28				
	Junction Capacitance	$V_{IN} = 2.5V, f = 1MHz,$	0.08		0.15	pF		
G (2)		between I/O pins						
$C_{J}^{(2)}$		$V_{IN}= 2.5V, f = 1MHz,$		0.22	0.35	pF		
		any I/O pin to Ground		0.32				

 $Notes: (1) Measurements\ performed\ using\ a\ 100 ns\ Transmission\ Line\ Pulse (TLP)\ system.$

(2) Junction capacitance is measured in V_R =0 V_r F=1 MH_Z

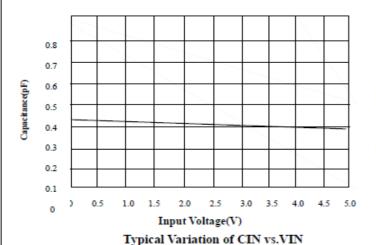
Symbol	Parameter		
$V_{\scriptscriptstyle \mathrm{RWM}}$	Working Peak Reverse Voltage		
$ m V_{\scriptscriptstyle BR}$	Breakdown Voltage @ IT		
Vc	Clamping Voltage @ Ipp 100ns		
	Transmission Line Pulse(TLP)		
I_{T}	Test Current		
$\mathbf{I}_{\scriptscriptstyle RM}$	Leakage current at VRWM		
$I_{ ext{PP}}$	Peak pulse current		
Co	Off-state Capacitance		
C_{J}	Junction Capacitance		

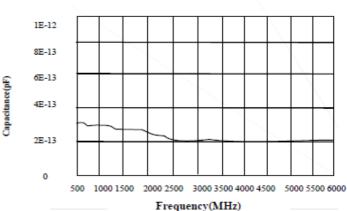


^{*}Other voltages may be available upon request.

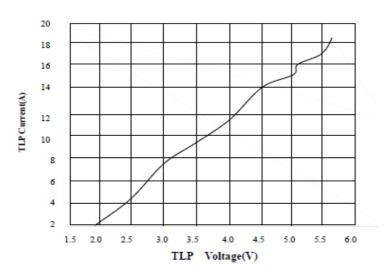


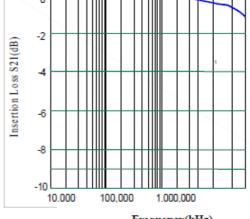
Typical electrical characterist applications





Capacitance vs. Frequency (IO to GND)





Transmission Line Pulsing (TLP) Measurement

Frequency(kHz)
Insertion Loss vs. Frequency
(IO to GND)

DCC 正式發行





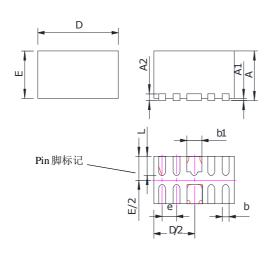
Package Information

DFN2510

Mechanical Data

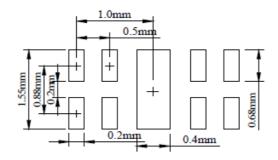
Case:DFN2510

Case Material: Molded Plastic. UL Flammability

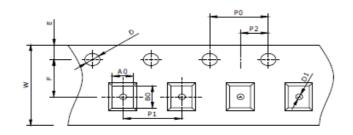


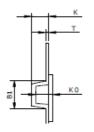
DIM	Millimeters		Inches		
	Min	Max	Min	Max	
A	0.45	0.65	0.018	0.026	
Al	0.05REF		0.002REF		
A2	0.15REF		0.006REF		
b	0.15	0.25	0.006	0.010	
bl	0.30	0.50	0.012	0.020	
D	2.424	2.576	0.095	0.101	
E	0.924	1.076	0.036	0.042	
e	0.50REF		0.020REF		
L	0.30 0.45		0.012	0.018	

Recommended Pad outline



DFN2510 Reel Dim





Package	Chip Size	Pocket Size	Tape	Reel Diameter	Quantity Per Reel	P0	Pl
Tackage	(mm)	B0×A0×K0(mm)	Width	Reef Diameter	Quantity Tel Reel	10	11
DFN2510	2.50×1.00×0.60	2.70×1.20×0.80	8mm	178mm(7")	3000	4mm	4mm
D0	D1	Е	F	K	T	W	
1.5mm	0.2mm	1.75mm	3.5mm	0.65mm	0.2mm	8mm	

